

Spring 2002



EEE598D: Analog Filter & Signal Processing Circuits

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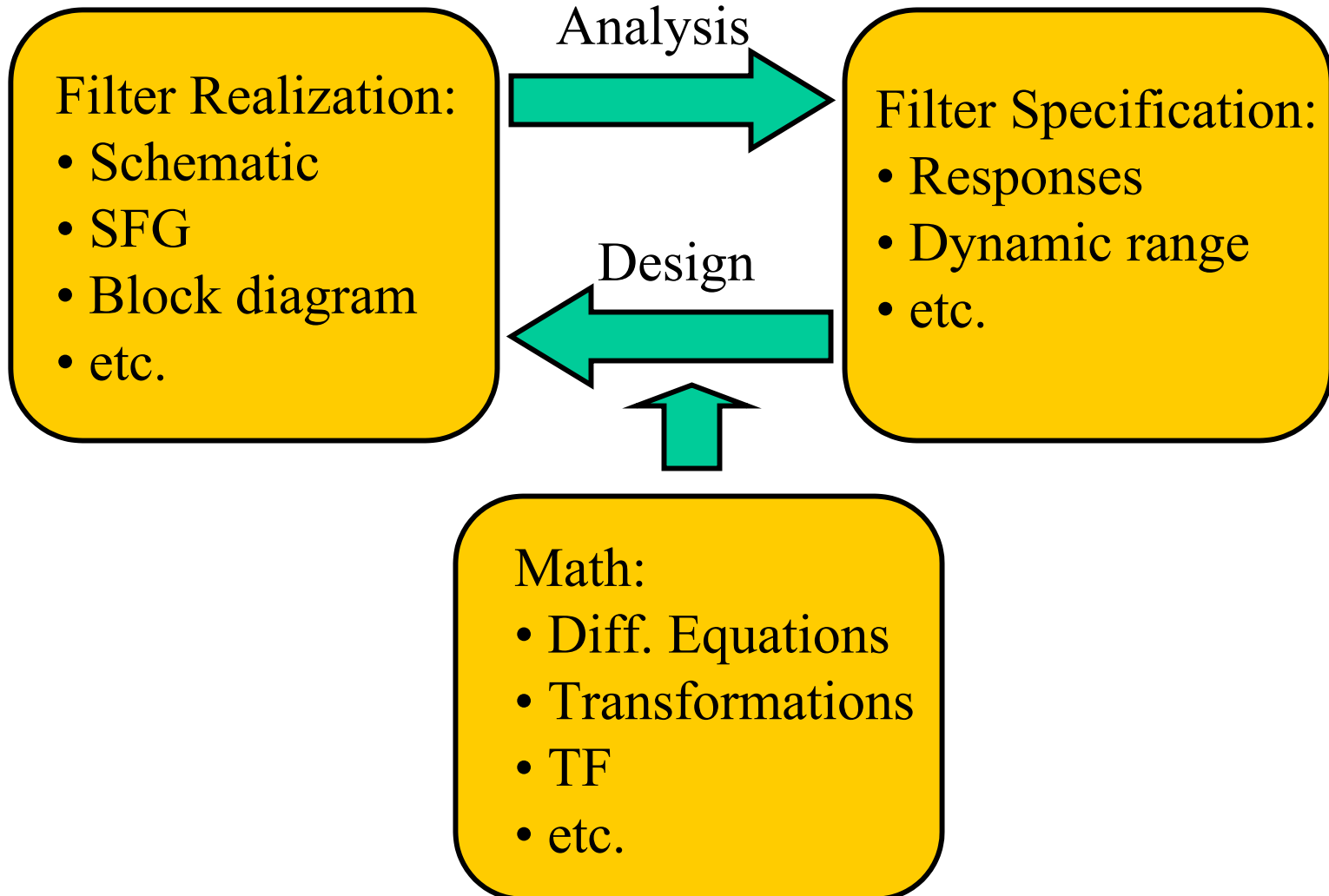
Thursday January 24, 2002



Today: Active RC & MOS-C Circuits

- Basic VLSI Passive & Active Components
- Tuning of Integrated CT Filters
- VCR Structures
- Basic Active RC and MOS-C Circuit Blocks

Typical Filter Design Problems

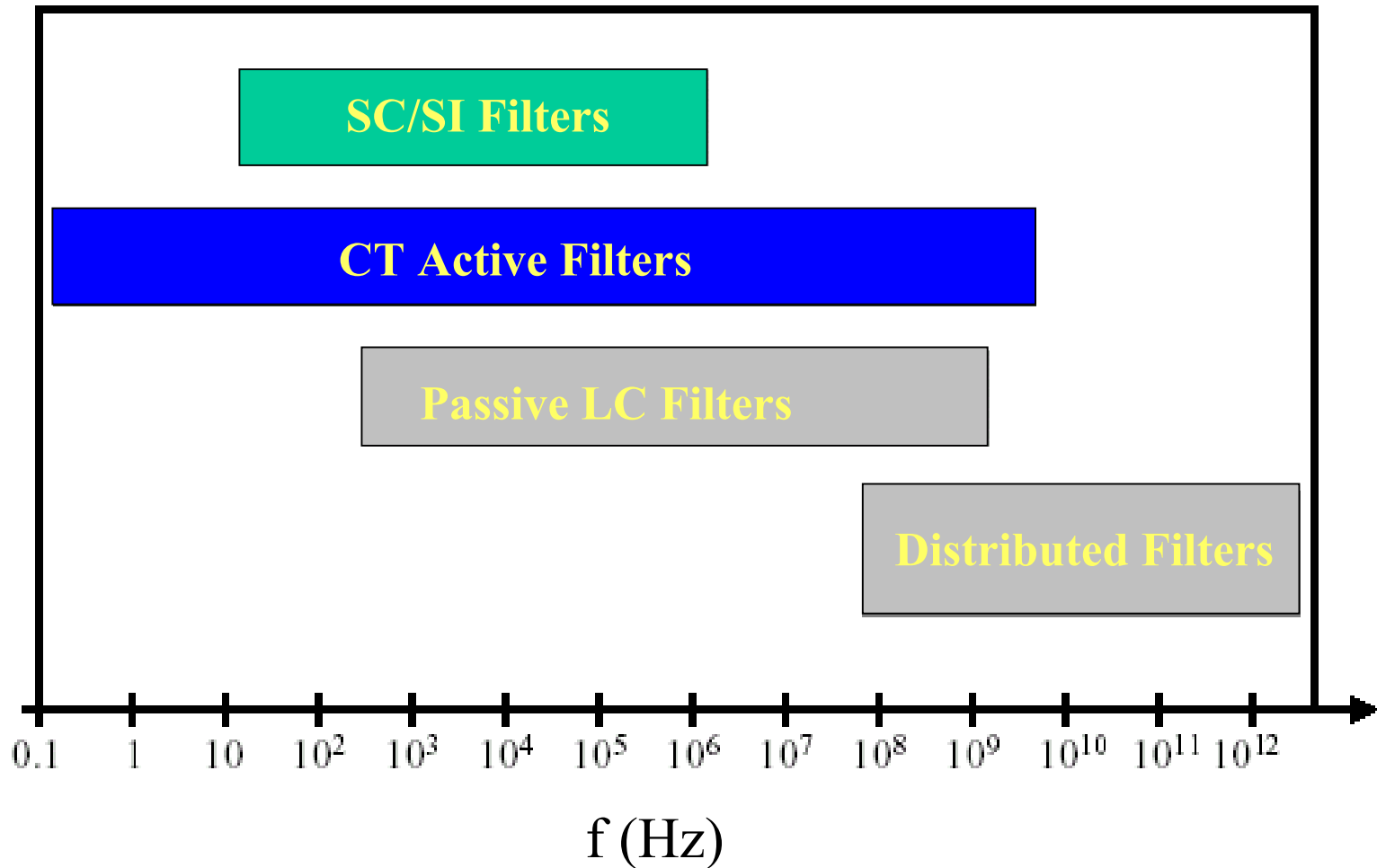


Desired Features for VLSI Filters



- Compatible with VLSI process
- Immunity to parasitic effects, fabrication tolerances, and environment variations
- Large dynamic range
- Good power supply rejection
- Low power and small chip area

Typical Operation Region of VLSI Filters



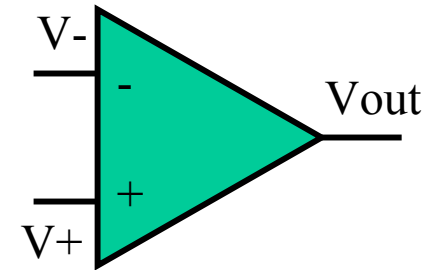
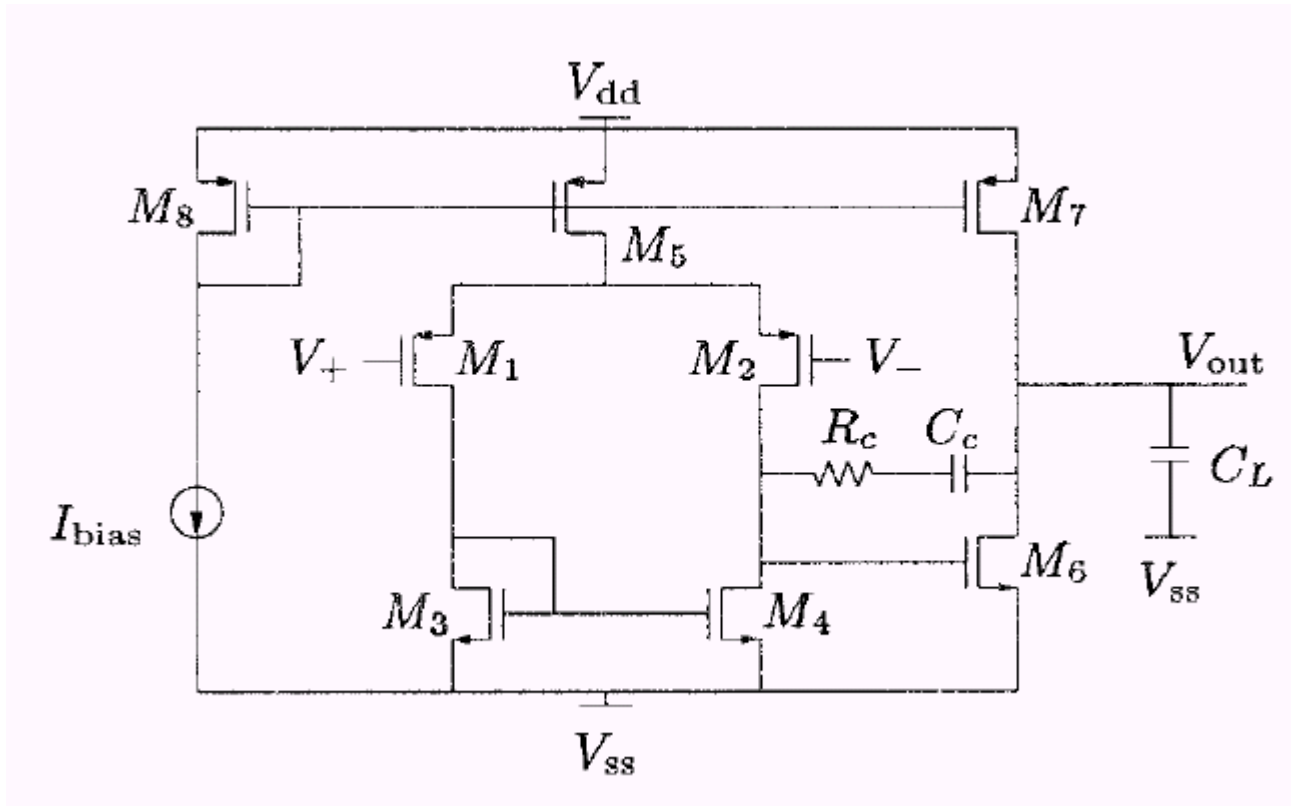
VLSI Active RC and MOS-C Filters



- Direct mapping of discrete active RC filters to VLSI active RC filters with CMOS compatible R, C, and Opamp realization.
- For MOS-C filters, resistors are mapped to MOS VCRs.
- Tuning is usually required due to parameter variation of the VLSI components.

CMOS Opamp Structures

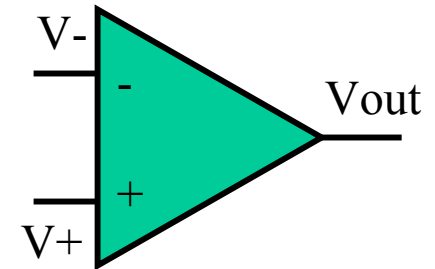
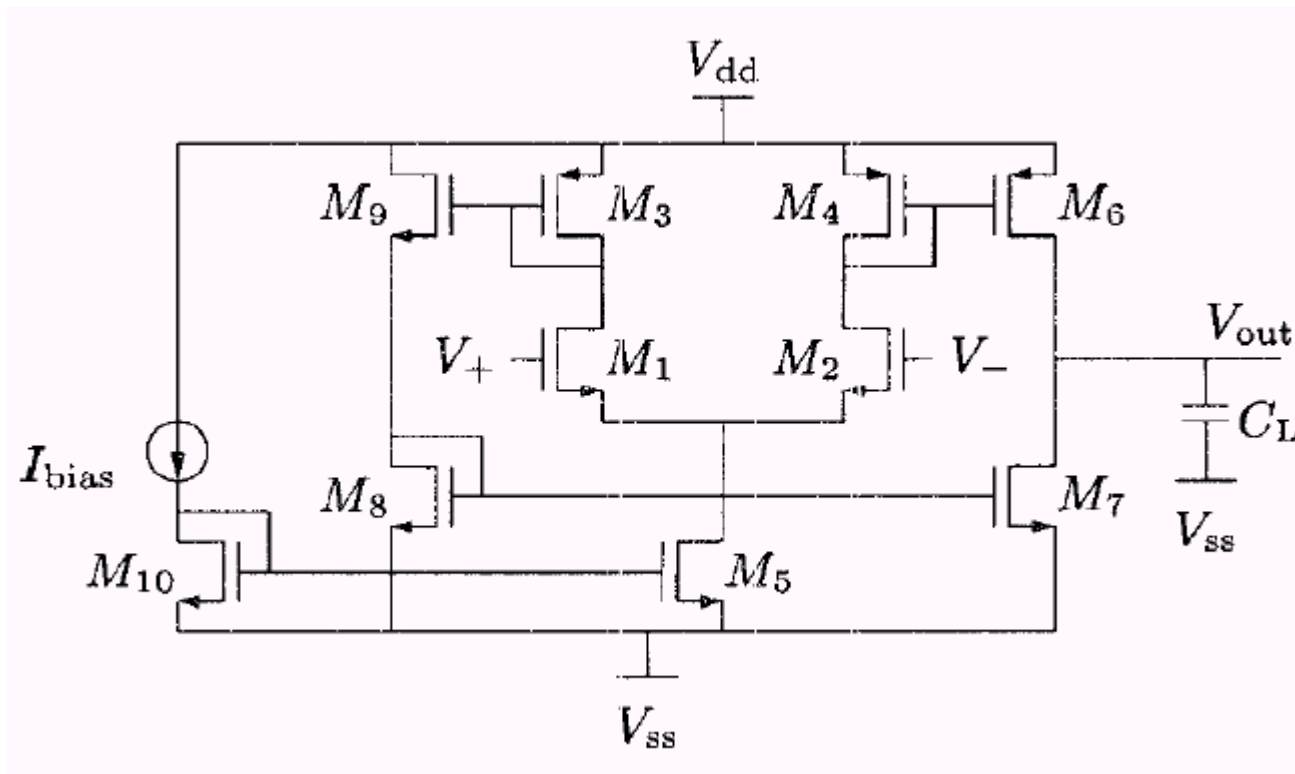
- 2-stage Opamp



CMOS Opamp Structures



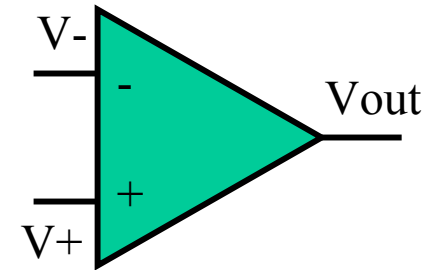
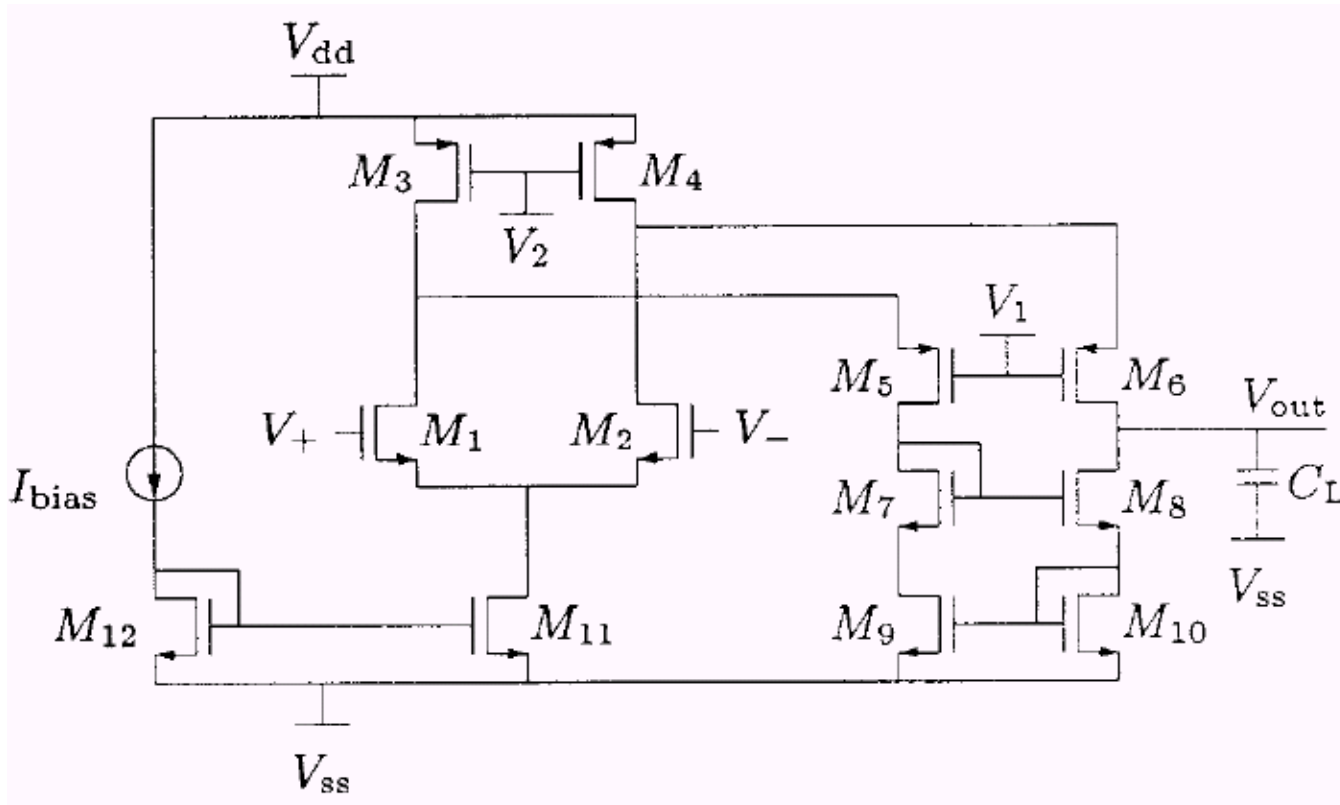
- OTA



CMOS Opamp Structures

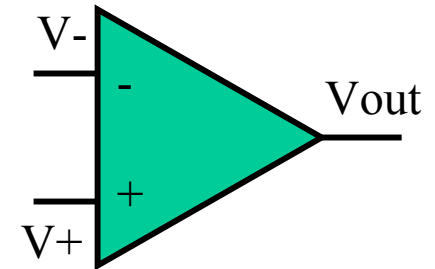
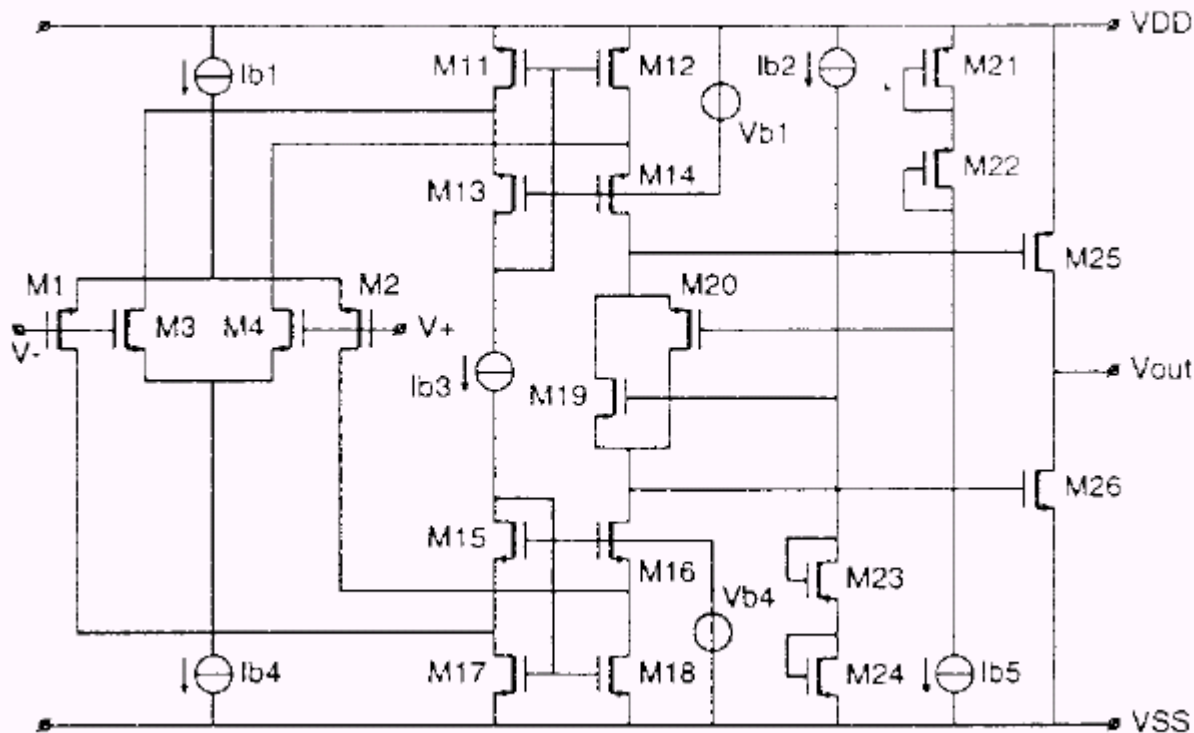


- Folded Cascode Opamp



CMOS Opamp Structures

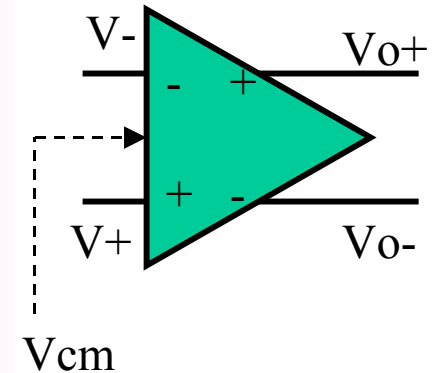
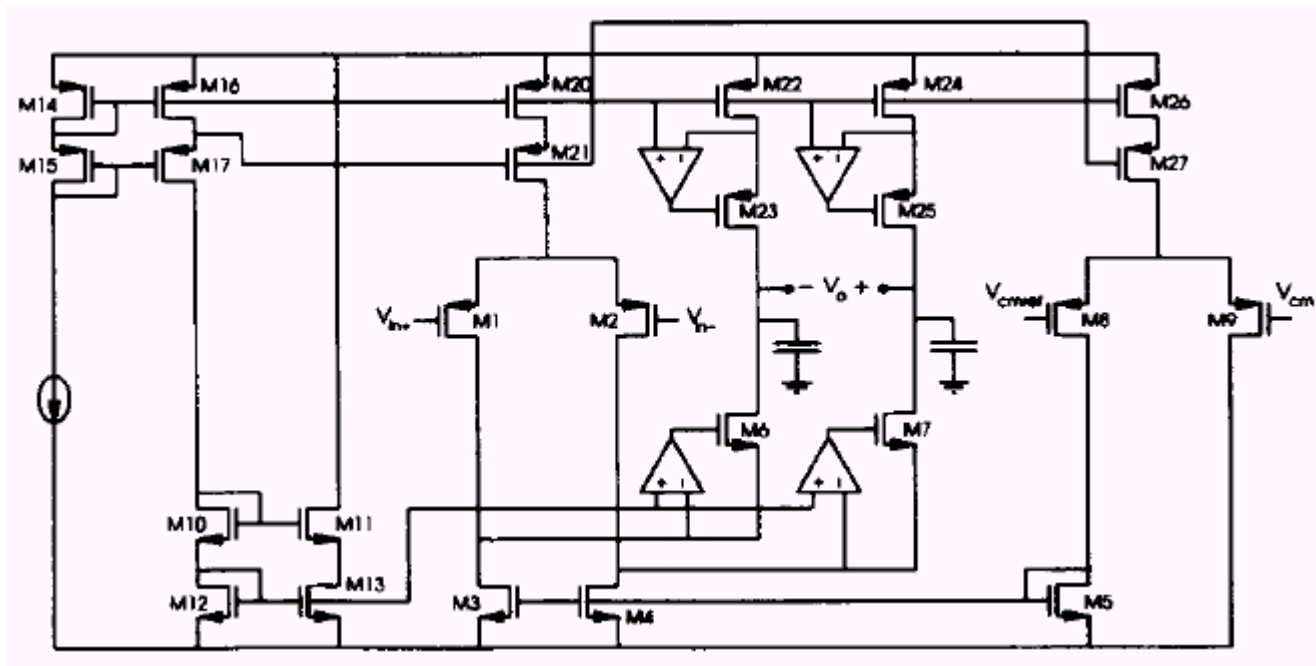
- Rail-to-rail Opamp



CMOS Opamp Structures



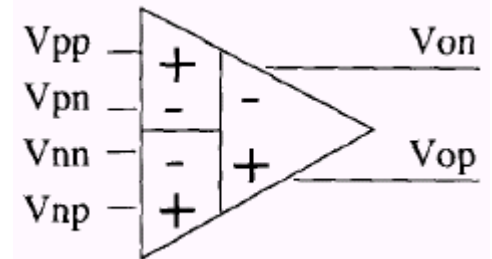
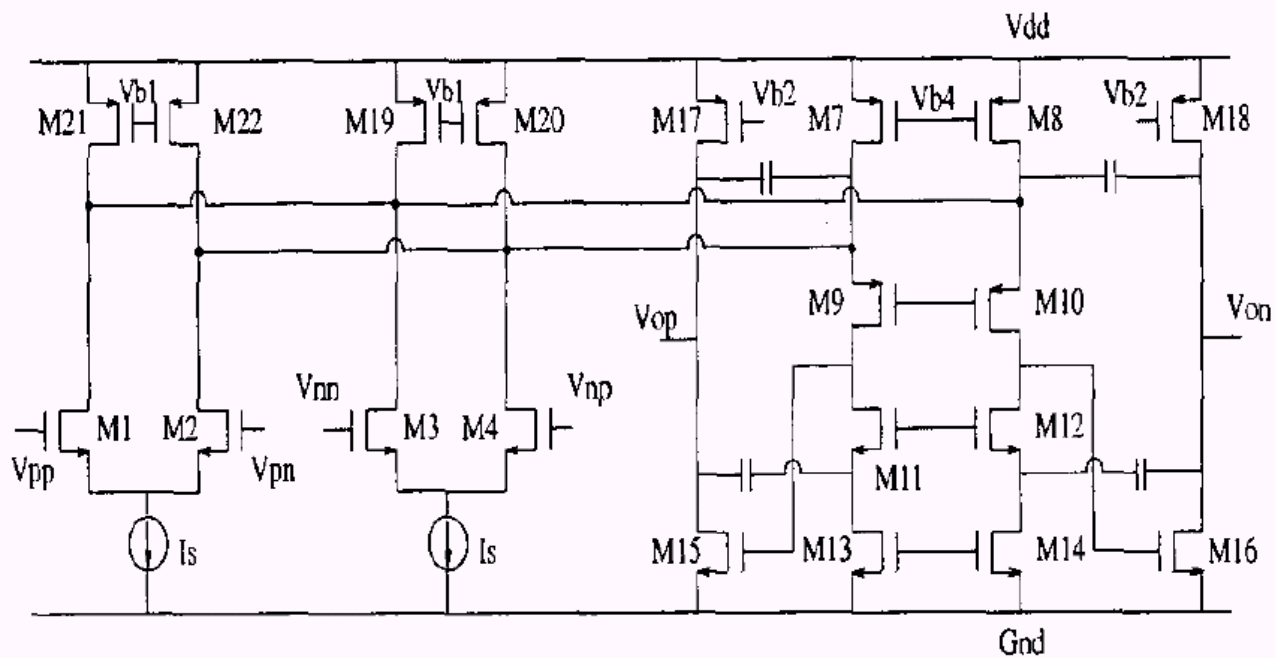
- Fully Differential Opamp



CMOS Opamp Structures

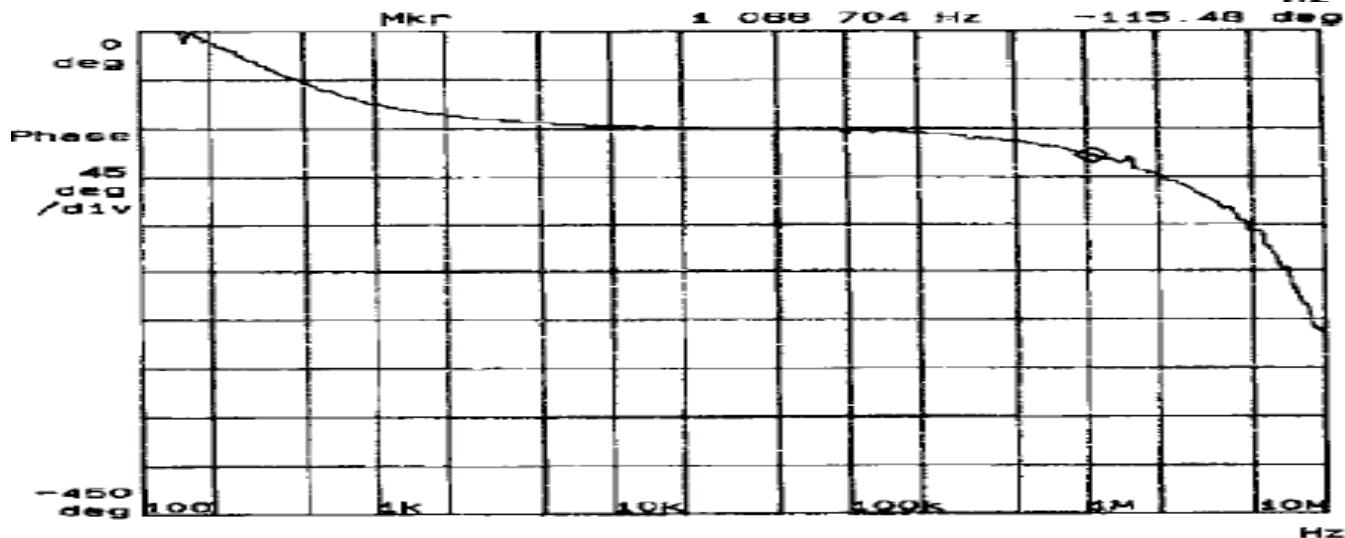
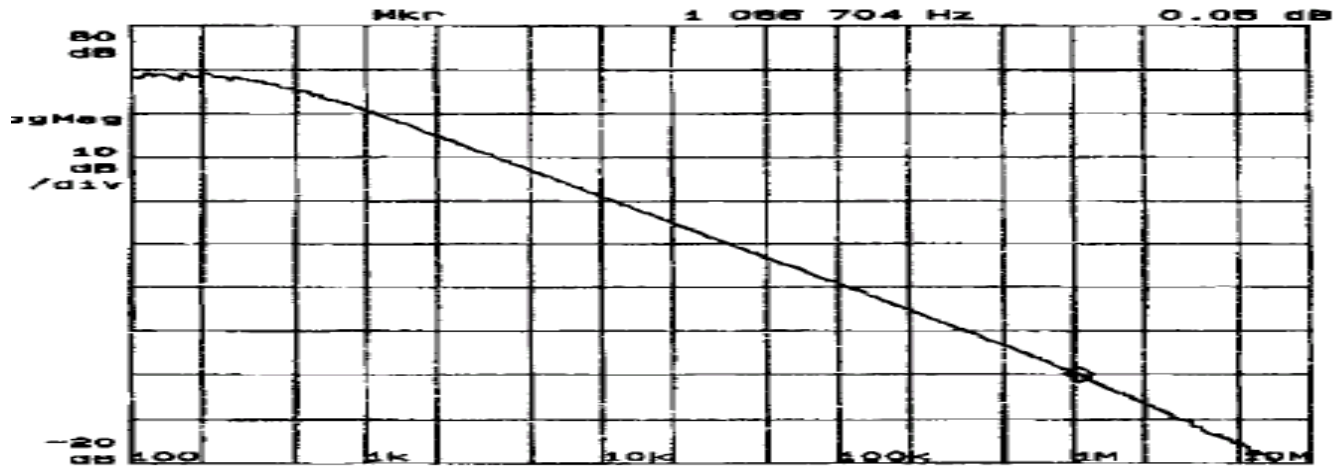


- Differential Difference Amplifier (DDA)



$$V_o = V_{op} - V_{on} = A_0[(V_{pp} - V_{pn}) - (V_{np} - V_{nn})]$$

Typical Opamp Responses



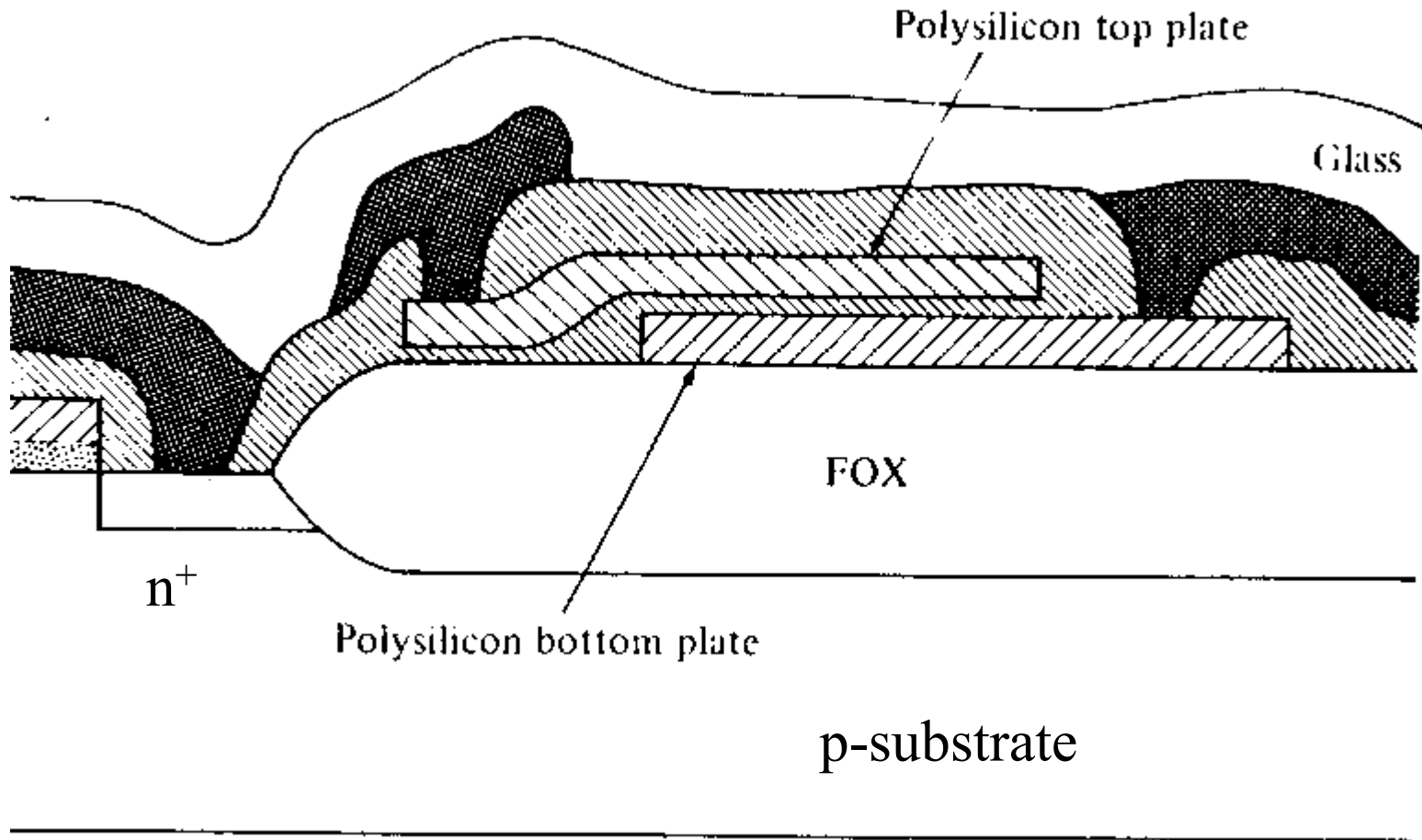
VLSI Capacitor Structures



- Gate capacitors
 - high density, but Nonlinear
- Junction capacitors
 - Highly nonlinear
- Poly(metal)-to-poly (metal) capacitors
 - Good linearity and high Q
- Fractal capacitor
 - High density and good linearity
 - More complicated structure

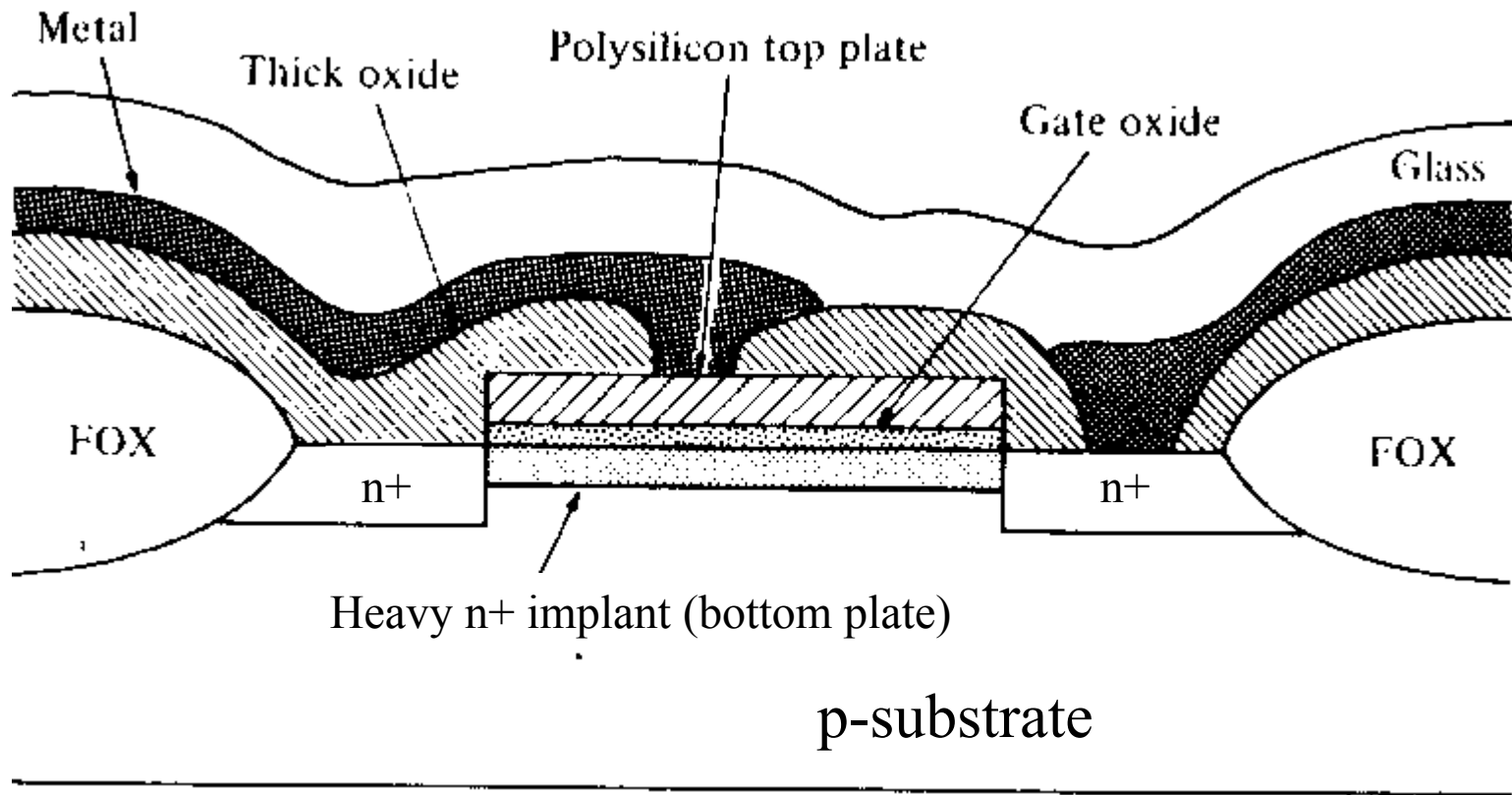
VLSI Capacitor Structures

- Double-Poly Capacitor



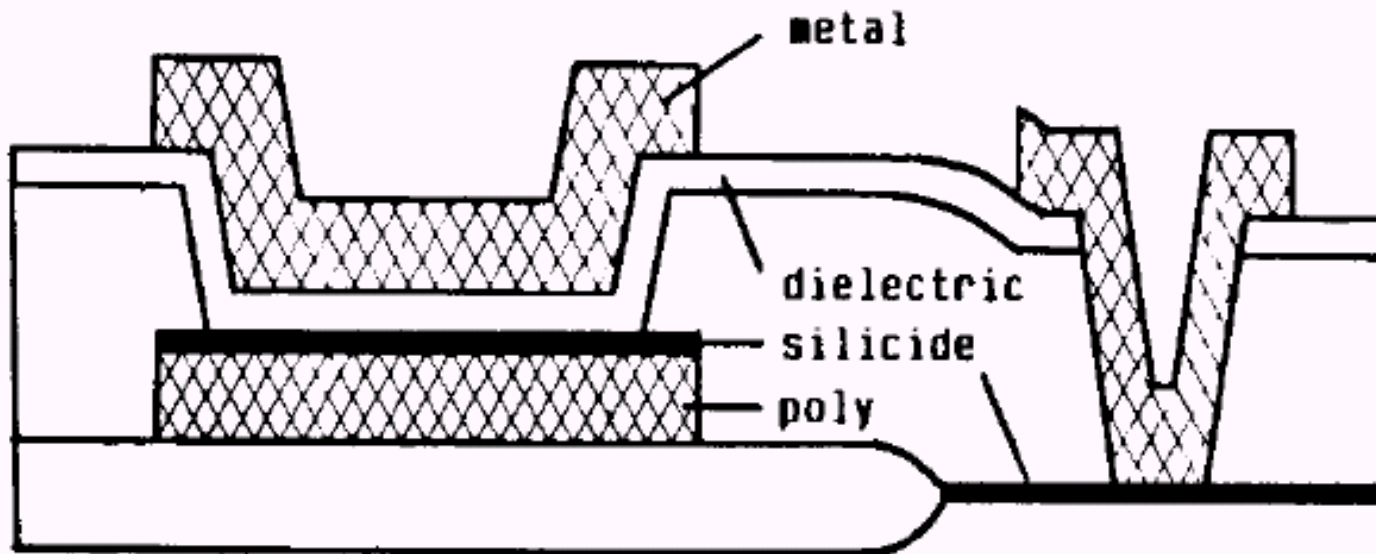
VLSI Capacitor Structures

- MOS Capacitor



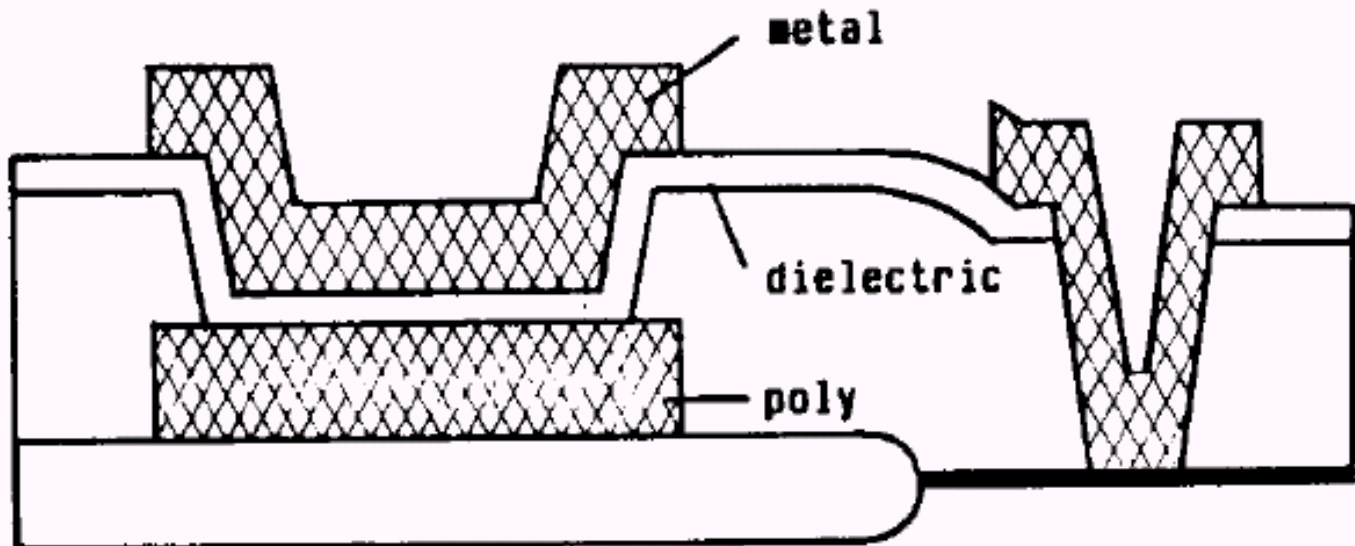
VLSI Capacitor Structures

- Metal-Polyicide Capacitor



VLSI Capacitor Structures

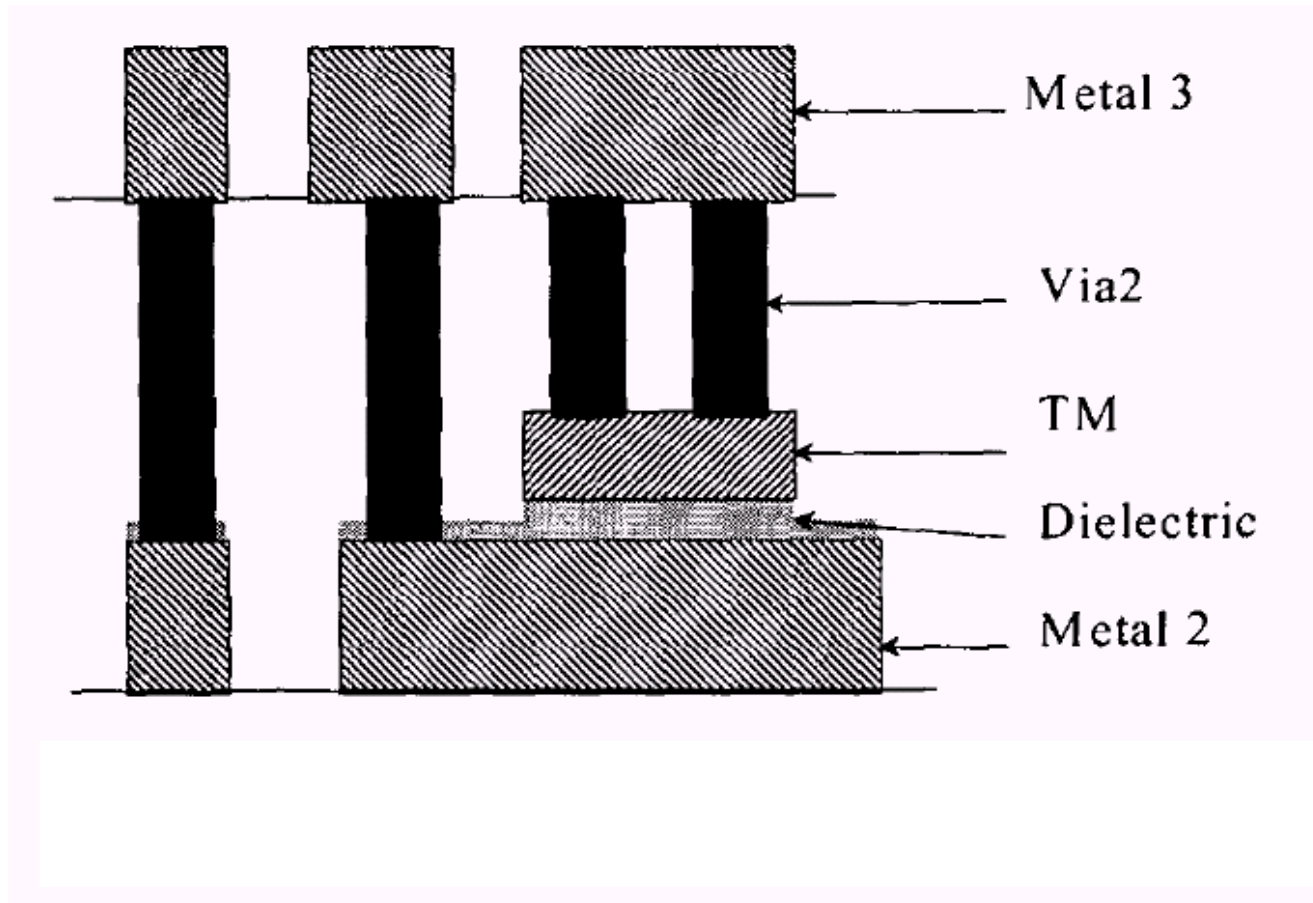
- Metal-Polyicide Capacitor



VLSI Capacitor Structures



- Metal-Insulator-Metal (MIM) Capacitor



MIM Capacitor Structure

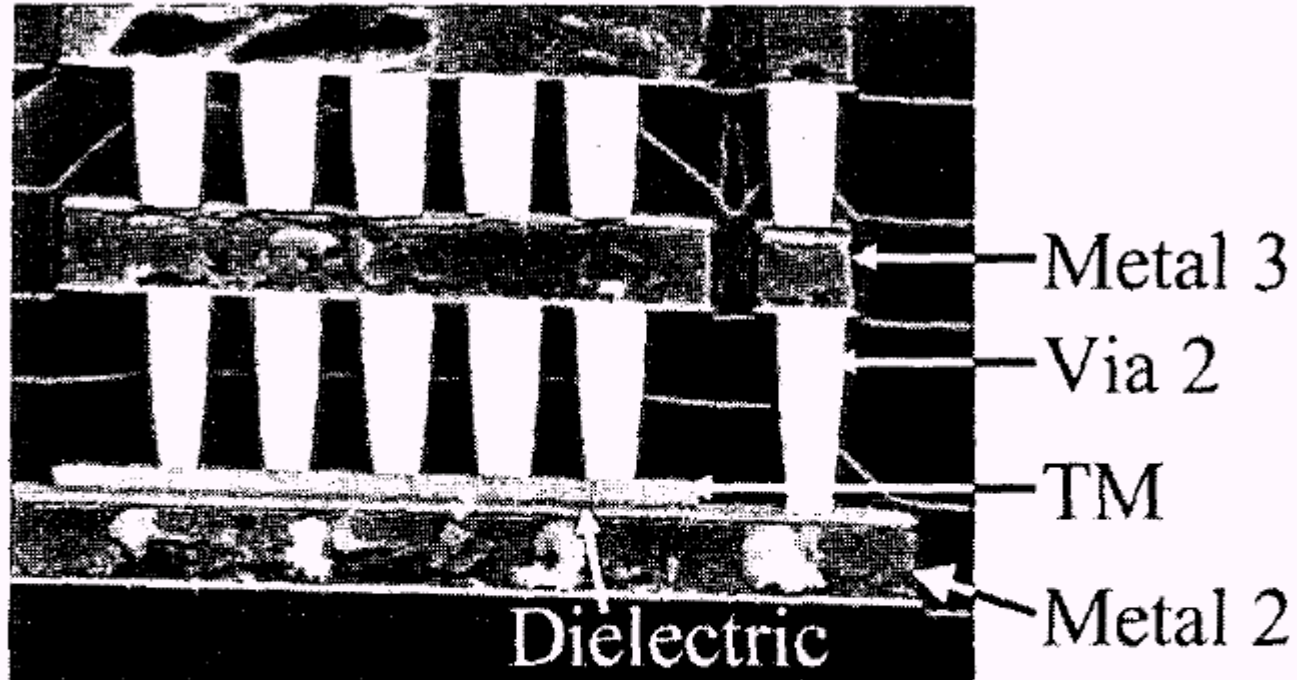
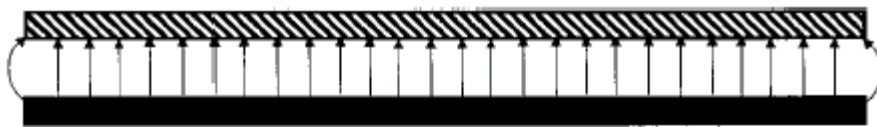


Fig. 2: Cross-section SEM photomicrograph across a typical MIM capacitor. Note that the shallow via 2 provides connectivity between top plate (TM) of capacitor to metal 3 and the deep via 2 provides connectivity of bottom plate (metal 2) to metal 3.

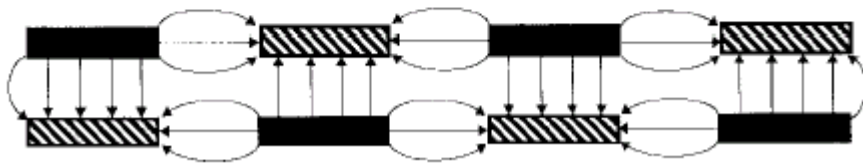
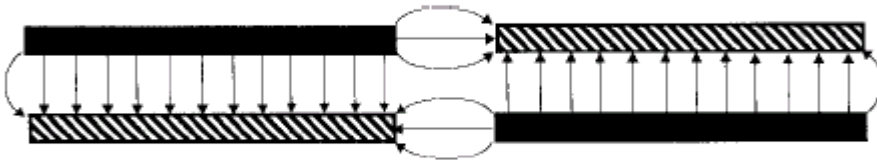
VLSI Capacitor Structures



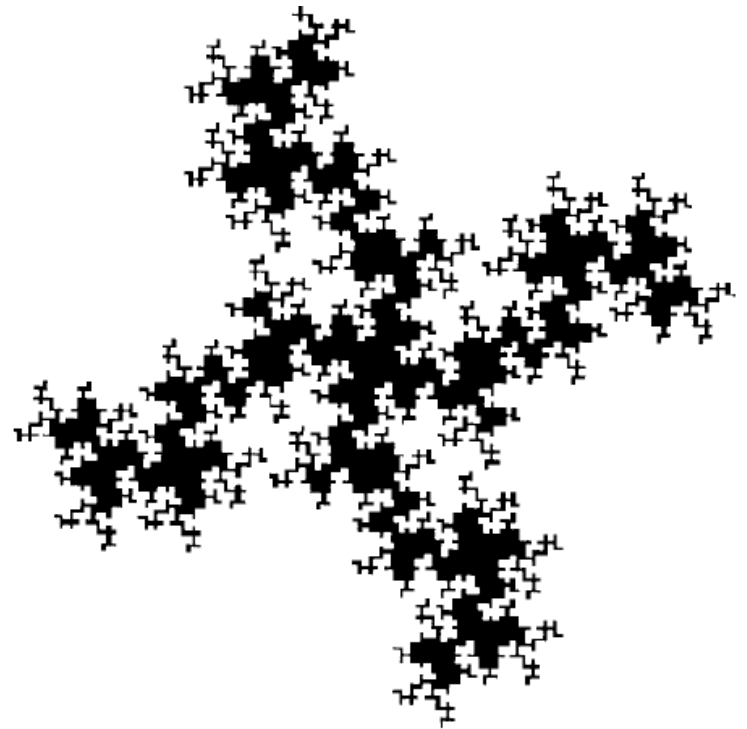
- Fractal capacitor



(a)



(b)



- Enhancement ($\sim 2.3x$) of capacitance/area with lateral coupling

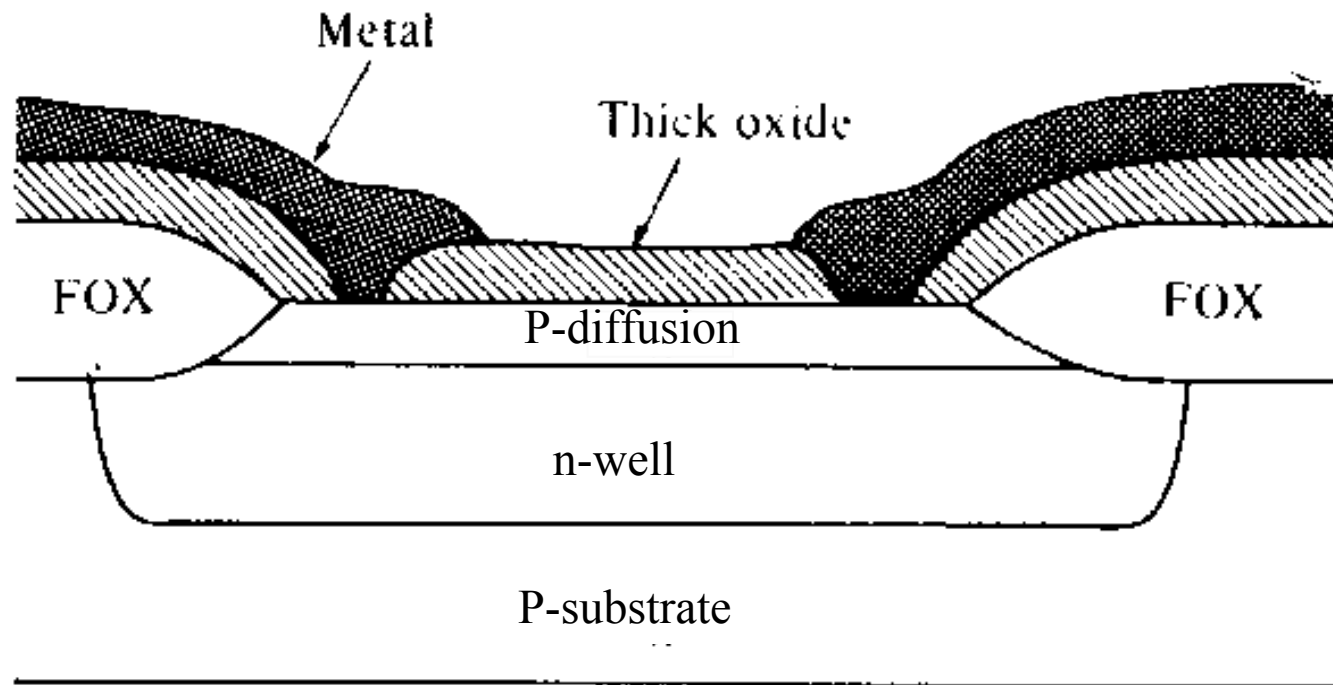
VLSI Resistor Structures



- Diffusion Resistors
- Poly Resistors
- Well Resistors
- Pinch Resistors

VLSI Resistor Structures

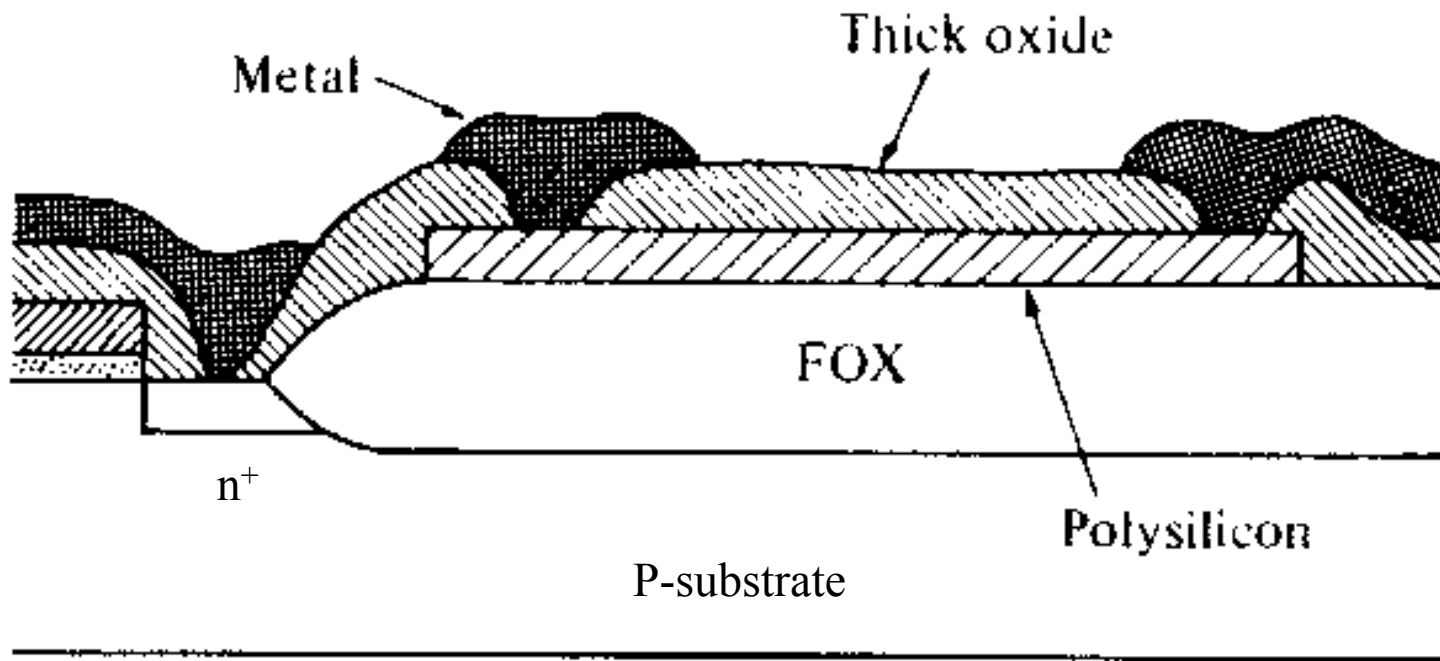
- Diffusion Resistor



VLSI Resistor Structures

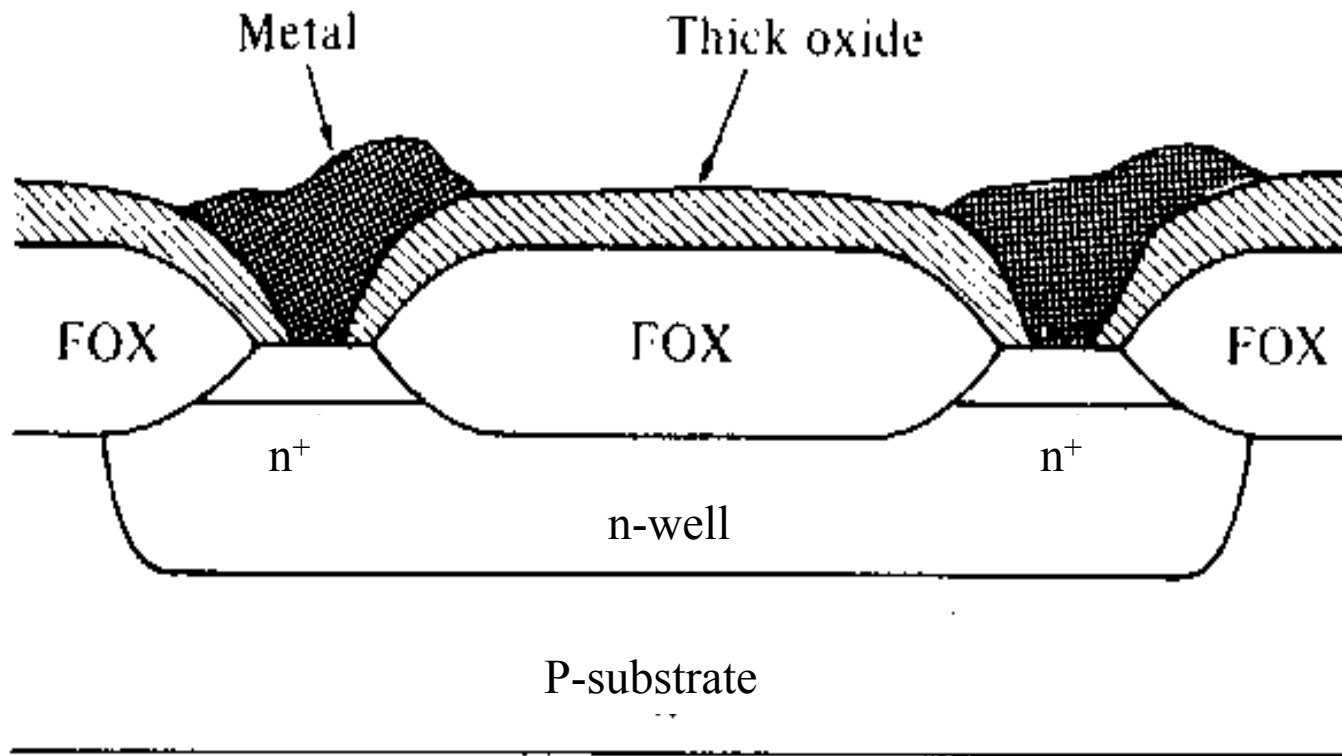


- Poly Resistor



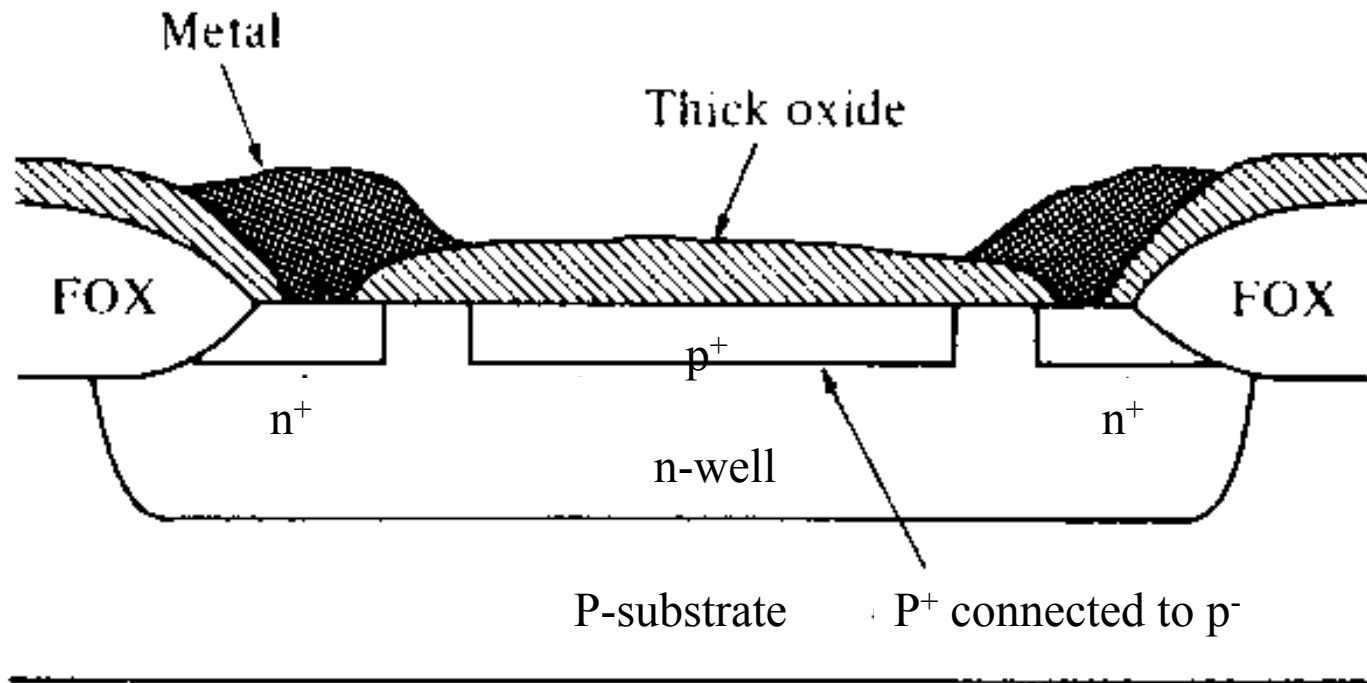
VLSI Resistor Structures

- Well Resistor



VLSI Resistor Structures

• Pinch Resistor



Example of Passive Element Accuracy



Approximate Performance Summary of CMOS Passive Components.

Component Type	Range of Values	Relative Accuracy	Temperature Coefficient	Voltage Coefficient	Absolute Accuracy
Poly/poly capacitor	0.3–0.4 fF/ μ^2	0.06%	25 ppm/ $^{\circ}$ C	50 ppm/V	20%
MOS capacitor	0.35–0.5 fF/ μ^2	0.06%	25 ppm/ $^{\circ}$ C	20 ppm/V	10%
Diffused resistor	10–100 ohms/sq.	2% (5 μ m width)	1500 ppm/ $^{\circ}$ C	200 ppm/V	35%
Poly resistor	30–200 ohms/sq.	2% (5 μ m width)	1500 ppm/ $^{\circ}$ C	100 ppm/V	30%
Ion impl. resistor	0.5–2k ohms/sq.	1% (5 μ m width)	400 ppm/ $^{\circ}$ C	800 ppm/V	5%
p-well resistor	1–10k ohms/sq.	2%	8000 ppm/ $^{\circ}$ C	10k ppm/V	40%
pinch resistor	5–20k ohms/sq.	10%	10k ppm/ $^{\circ}$ C	20k ppm/V	50%

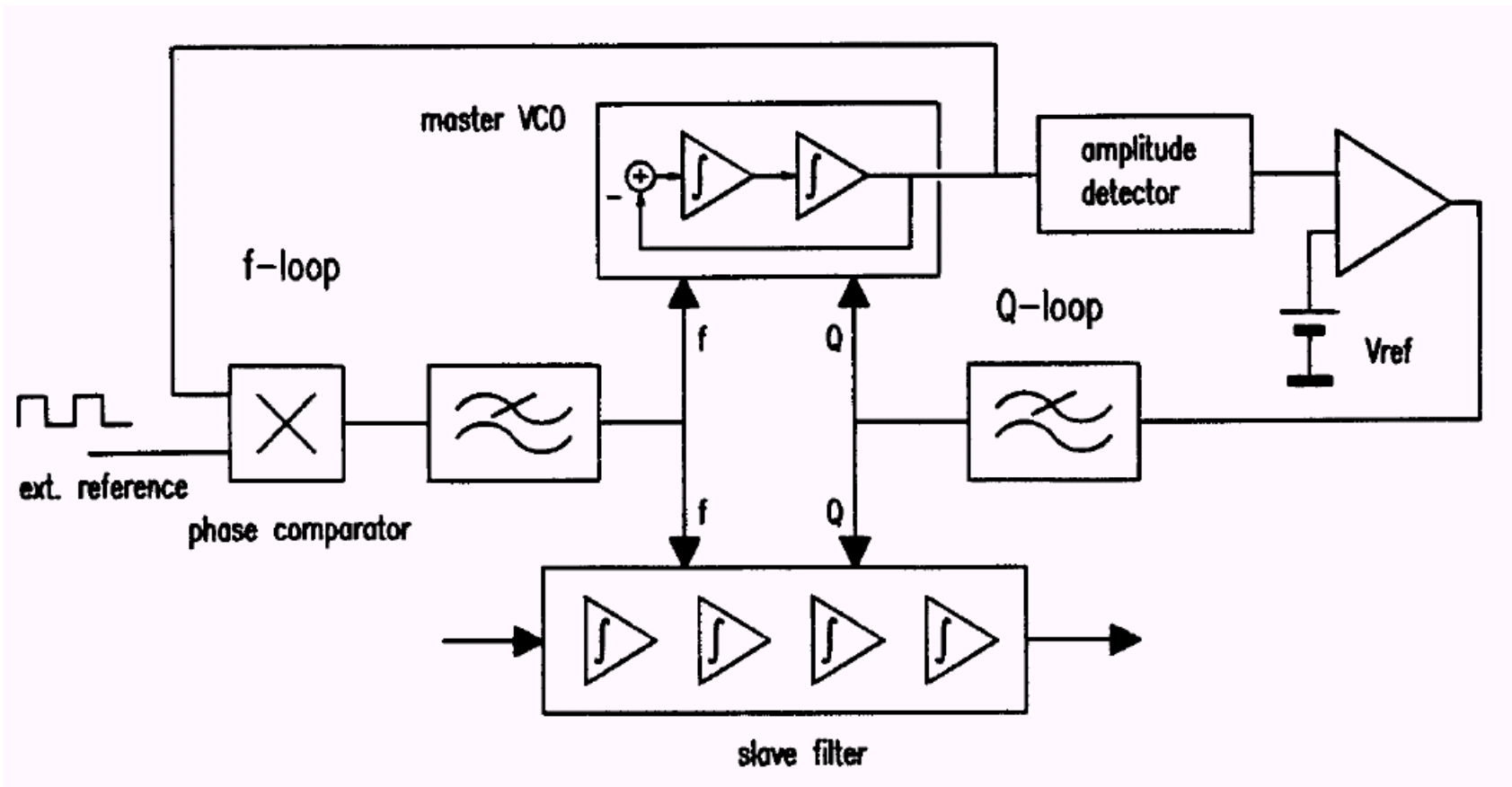
Tuning of VLSI CT Filters



- Tuning required for CT integrated filters to account for capacitance and resistance/transconductance variations — 30% time-constant variations
- Must account for process, temperature, aging, etc.
- While absolute tolerances high, ratio of two like components can be matched to under 1%
- Tuning can often be the MOST difficult part of a CT integrated filter design
- Note that SC/SI filters do not need tuning as their transfer-function accuracy set by ratio of capacitors (or transistors) and a clock-frequency

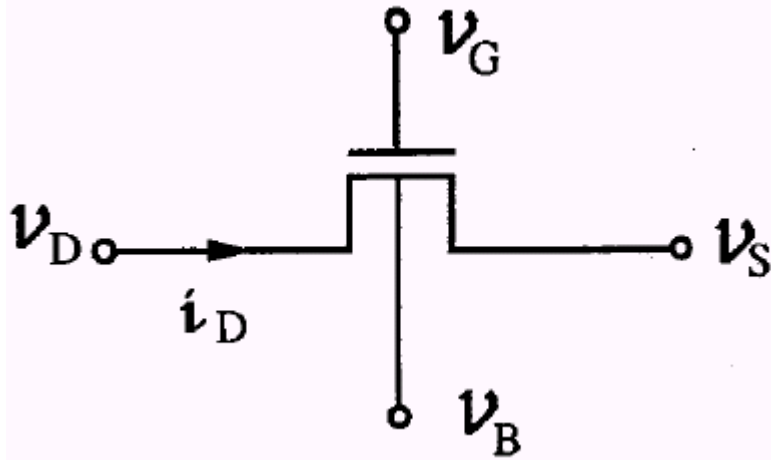
Tuning of VLSI CT Filters

- Example:



VLSI VCR Structures

- Basic MOS voltage controlled resistor (VCR)



$$I = \beta \left(V_G - V_T - \frac{V_d + V_s}{2} \right) (V_d - V_s)$$

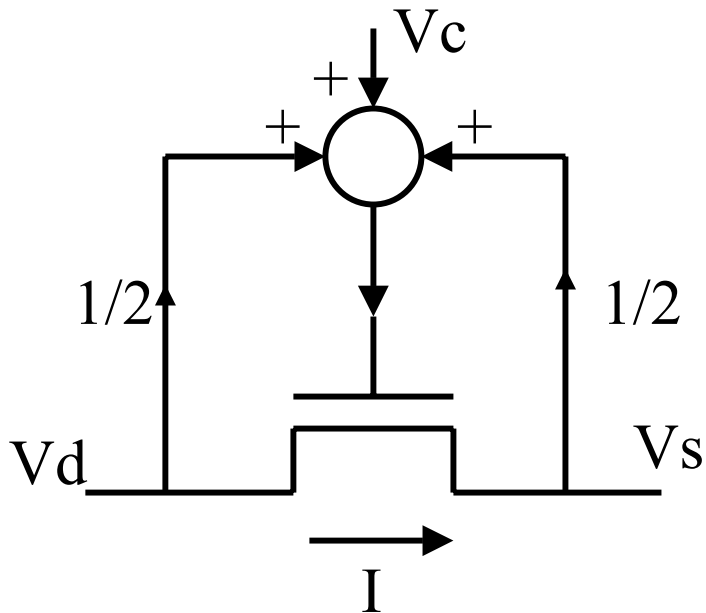
$$R = \frac{1}{\beta \left(V_G - V_T - \frac{V_d + V_s}{2} \right)}$$

Control voltage

Nonlinear term

VLSI VCR Structures

- Linear MOS VCR - 1st approach



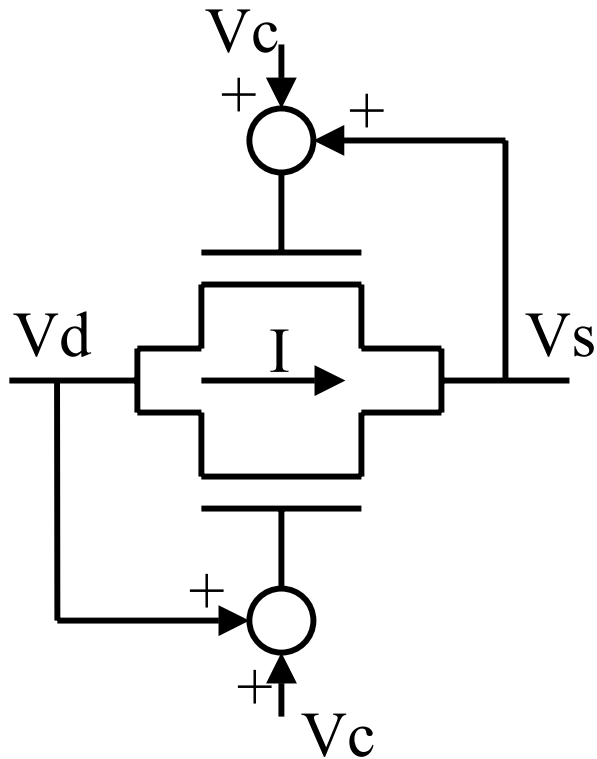
Control voltage

$$\text{Let } V_G = \frac{V_d + V_s}{2} + V_c$$

$$\text{Then } R = \frac{1}{\beta(V_c - V_T)}$$

VLSI VCR Structures

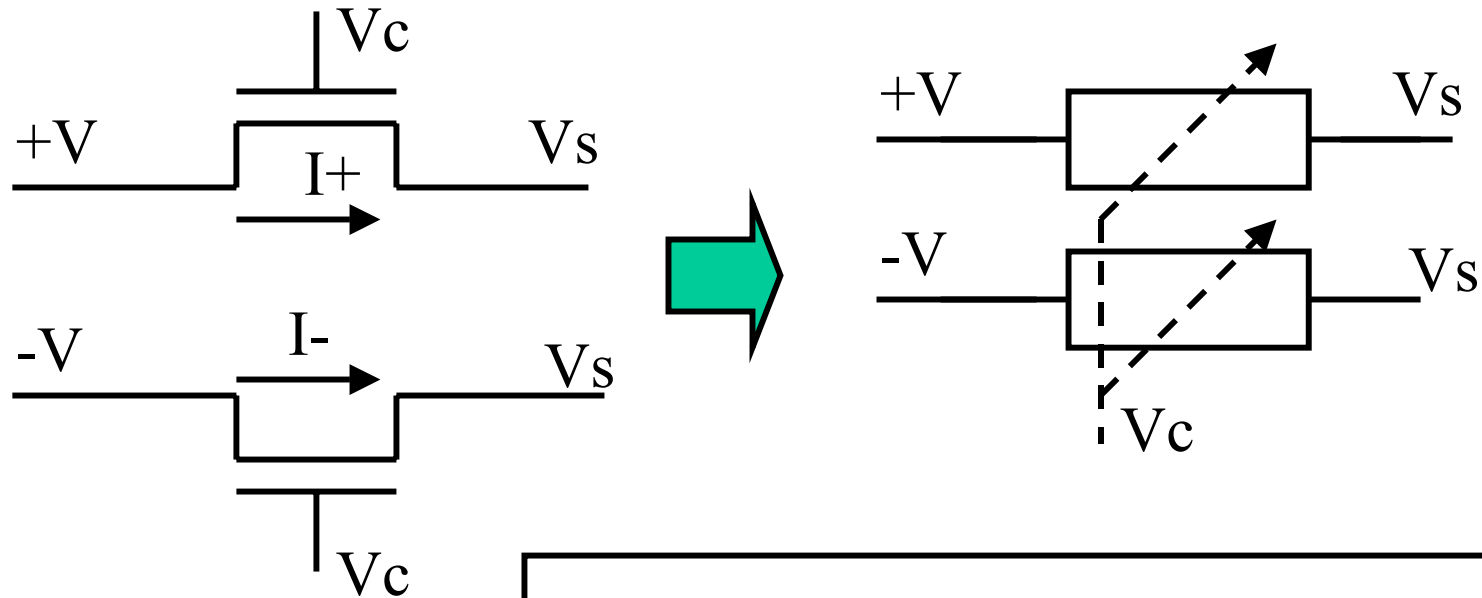
- Linear MOS VCR - 2nd approach



$$\begin{aligned} I &= \beta \left(V_c + V_d - V_T - \frac{V_d + V_s}{2} \right) (V_d - V_s) \\ &+ \beta \left(V_c + V_s - V_T - \frac{V_d + V_s}{2} \right) (V_d - V_s) \\ &= 2\beta (V_{c_s} - V_T) (V_d - V_s) \\ R &= \frac{1}{2\beta (V_G - V_T)} \end{aligned}$$

VLSI VCR Structures

- Linear MOS VCR - 3rd approach



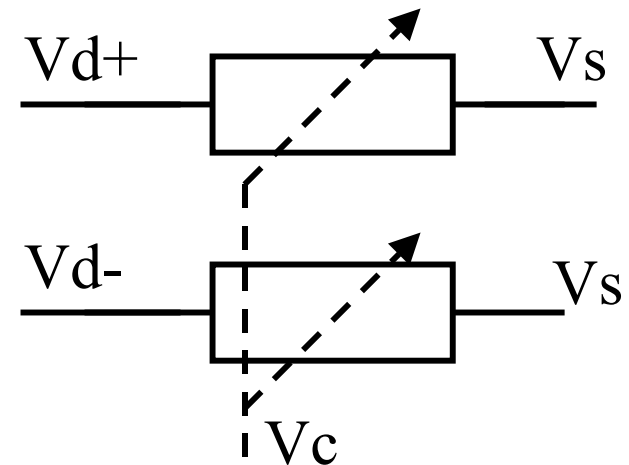
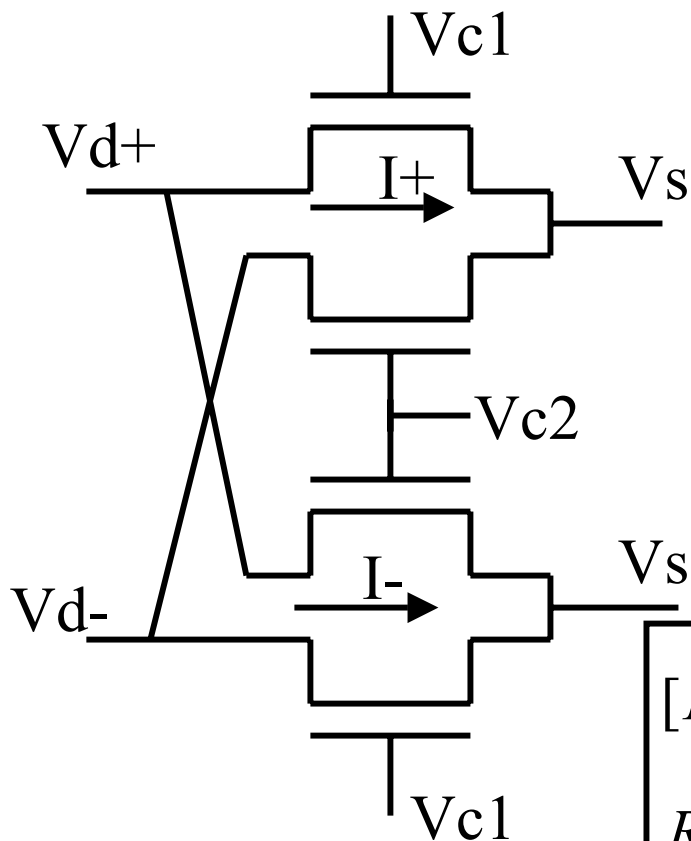
$$[I_+ - I_-] = \beta (V_C - V_T)[(+V - V_s) - (-V - V_s)]$$

$$R = \frac{1}{\beta (V_C - V_T)}$$

VLSI VCR Structures



- Linear MOS VCR - 4th approach

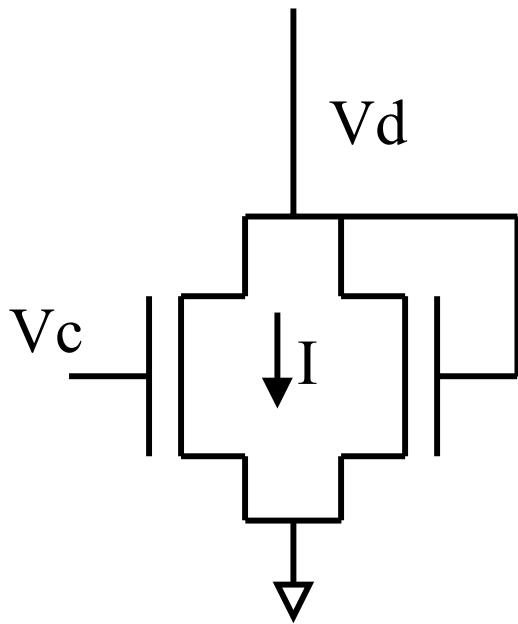


$$[I_+ - I_-] = \beta (V_{C2} - V_{C2}) [(V_{d+} - V_s) - (V_{d-} - V_s)]$$

$$R = \frac{1}{\beta (V_{C2} - V_{C2})}$$

VLSI VCR Structures

- Grounded Linear MOS VCR



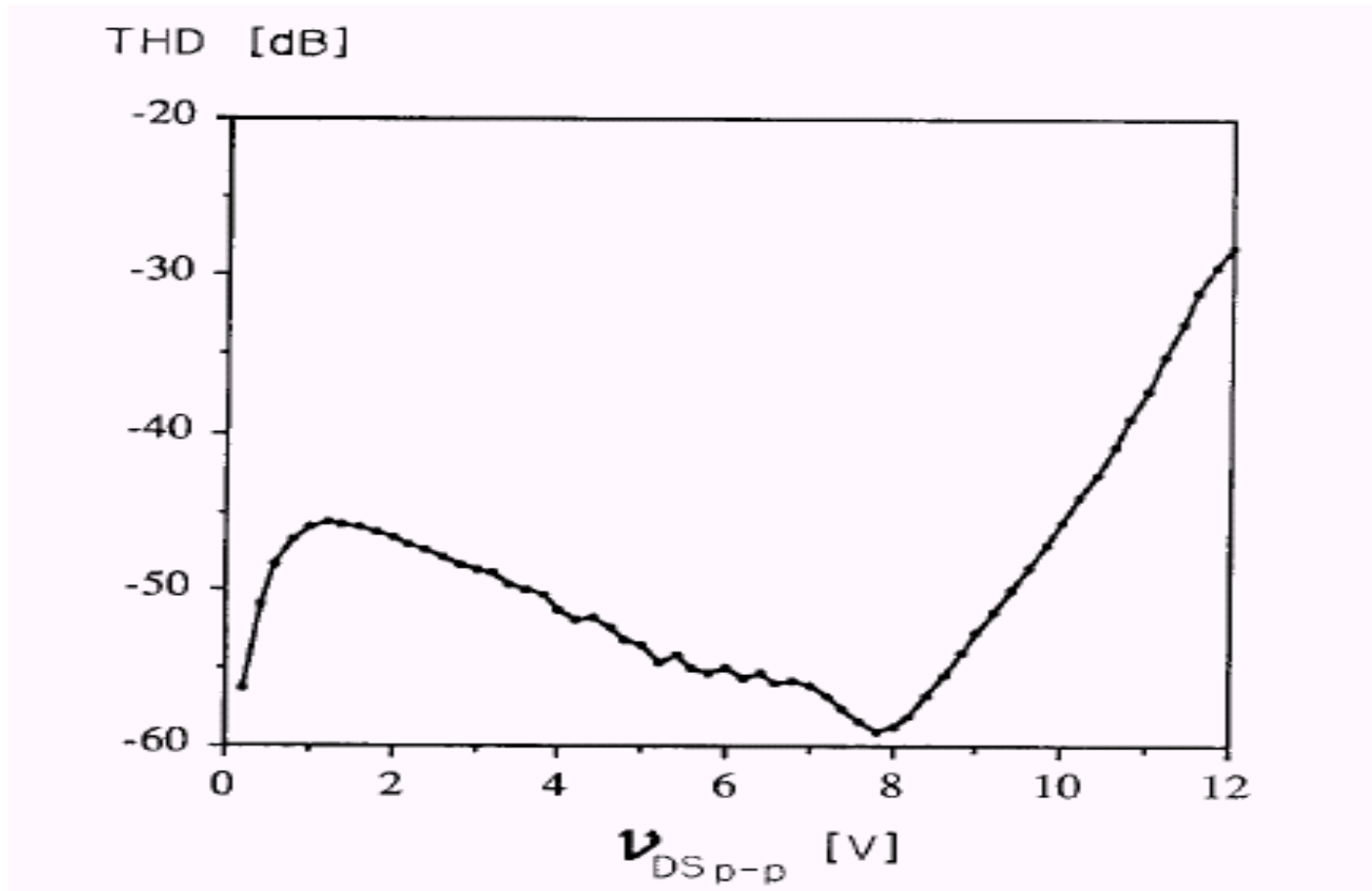
$$I = \frac{\beta}{2}(V_d - V_T)^2 + \beta(V_c - V_T - \frac{V_d}{2})V_d$$
$$= \beta(V_c - 2V_T)V_d + \frac{\beta}{2}(V_T)^2$$

$$R = \left(\frac{dI}{dV_d}\right)^{-1} = \frac{1}{\beta(V_c - 2V_T)}$$

VLSI Resistor Structures

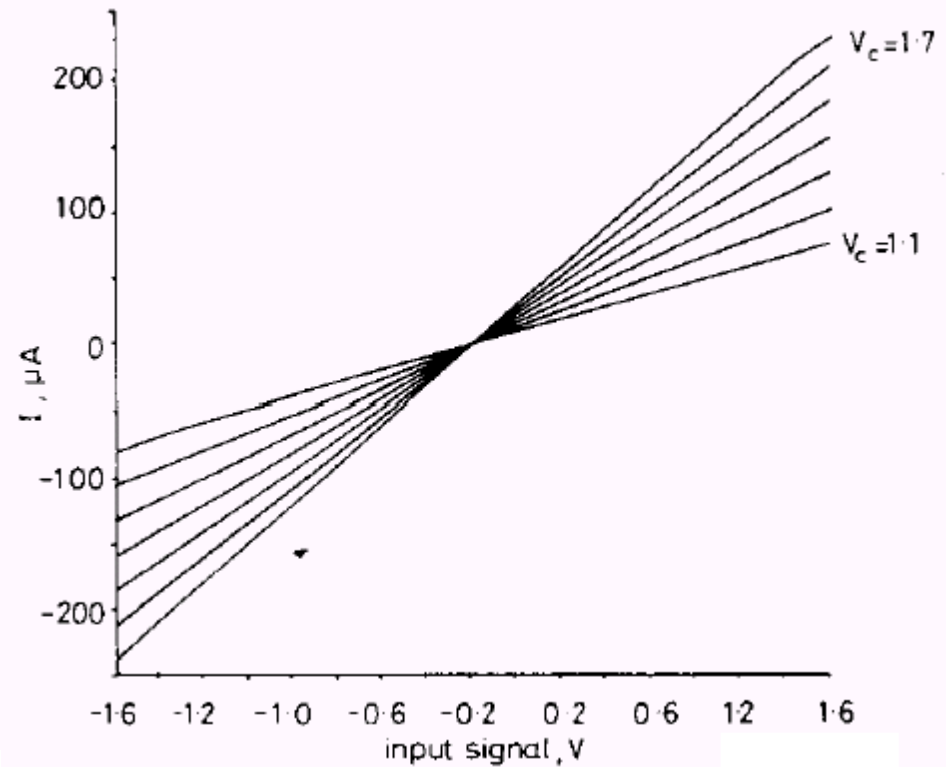
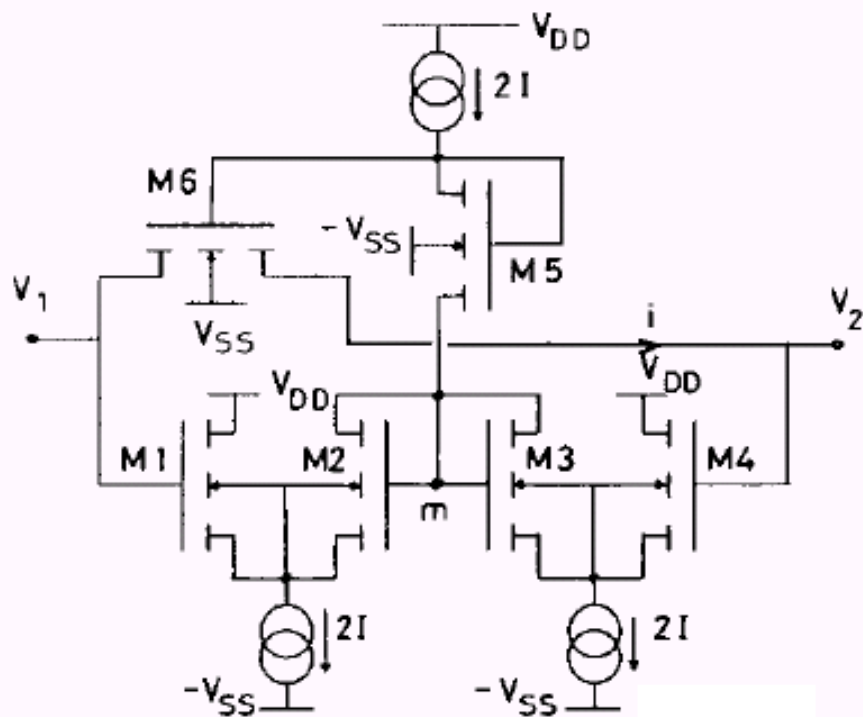


- MOS VCR Implementation



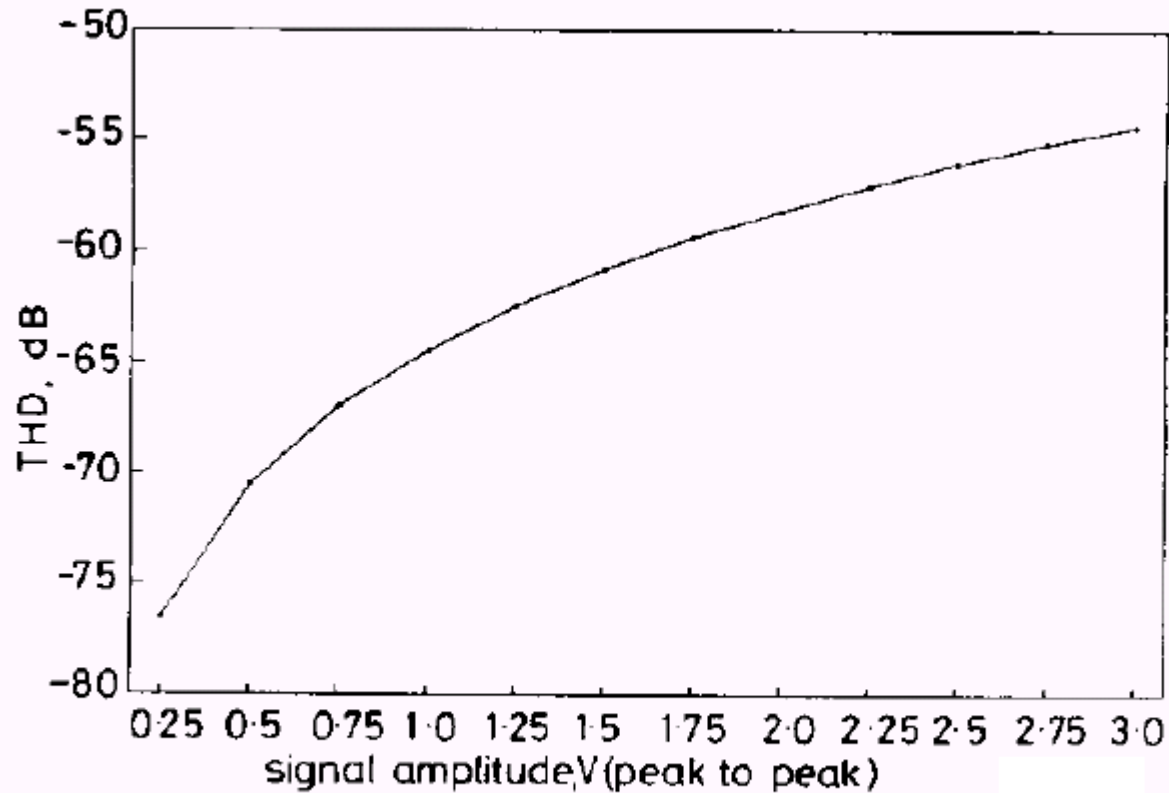
VLSI Resistor Structures

- MOS VCR Implementation



VLSI Resistor Structures

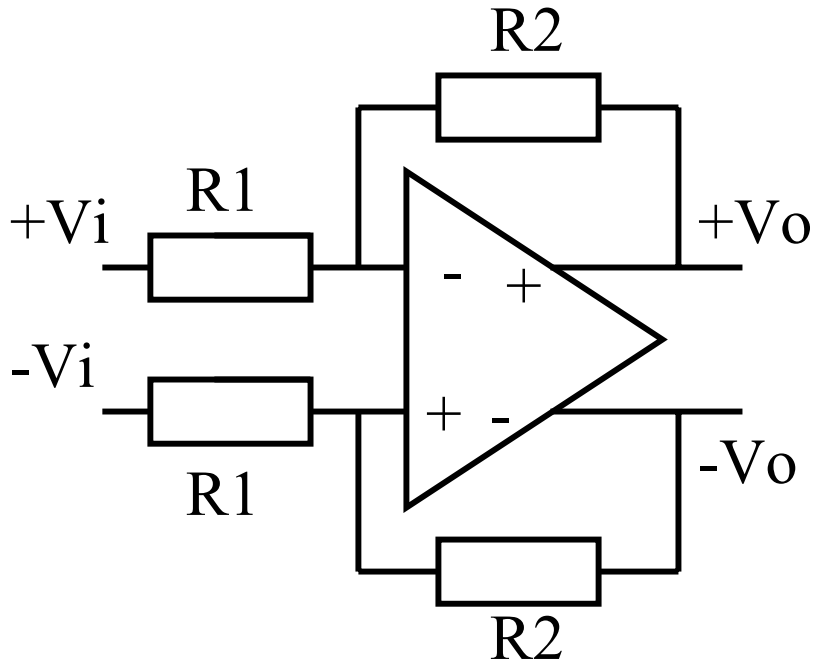
- MOS VCR Implementation



Distortion against signal amplitude (nominal resistance 10 k Ω)

Basic Active RC Circuits

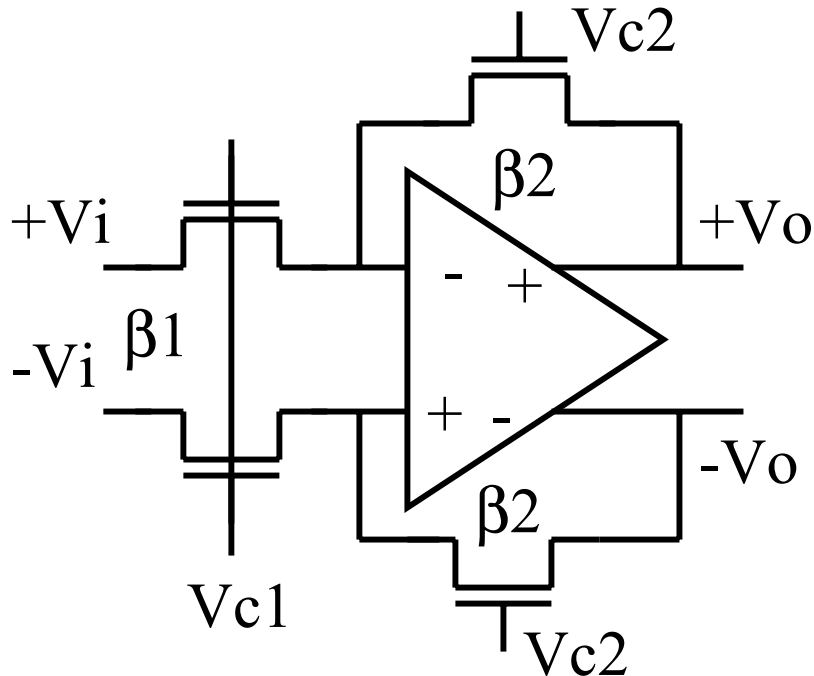
- Fully differential gain stage



$$\frac{V_o}{V_i} = -\frac{R_2}{R_1}$$

Basic MOS-C Circuits

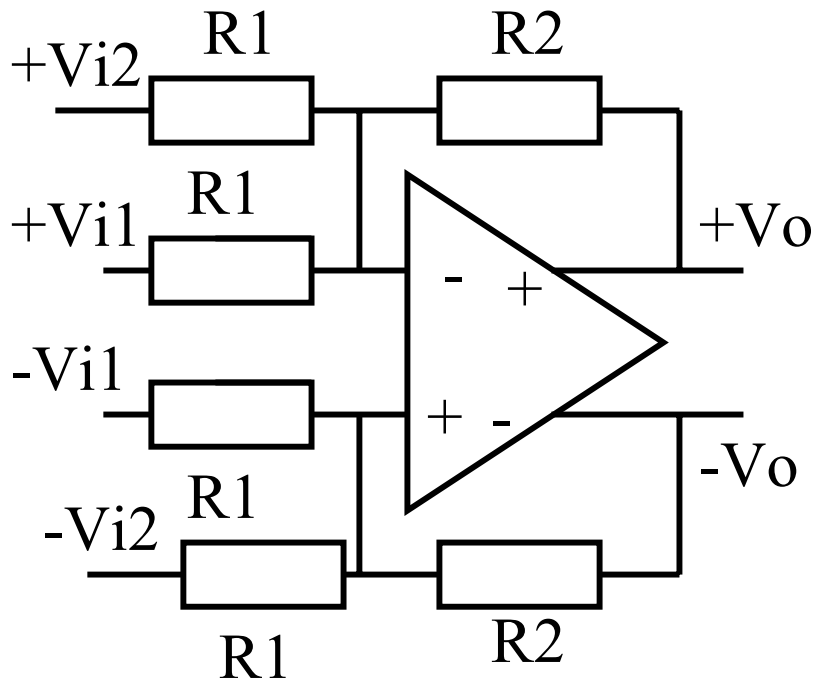
- Fully differential gain stage



$$\frac{V_o}{V_i} = -\frac{\beta_1(V_{c1} - V_T)}{\beta_2(V_{c2} - V_T)}$$

Basic Active RC Circuits

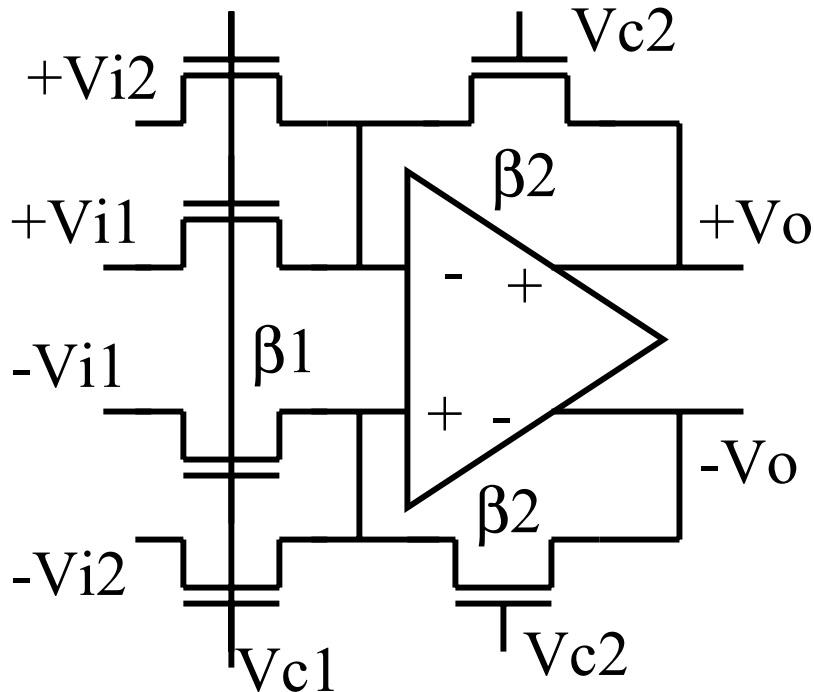
- Fully differential adder stage



$$V_o = -\frac{R_2}{R_1}(V_{i1} + V_{i2})$$

Basic MOS-C Circuits

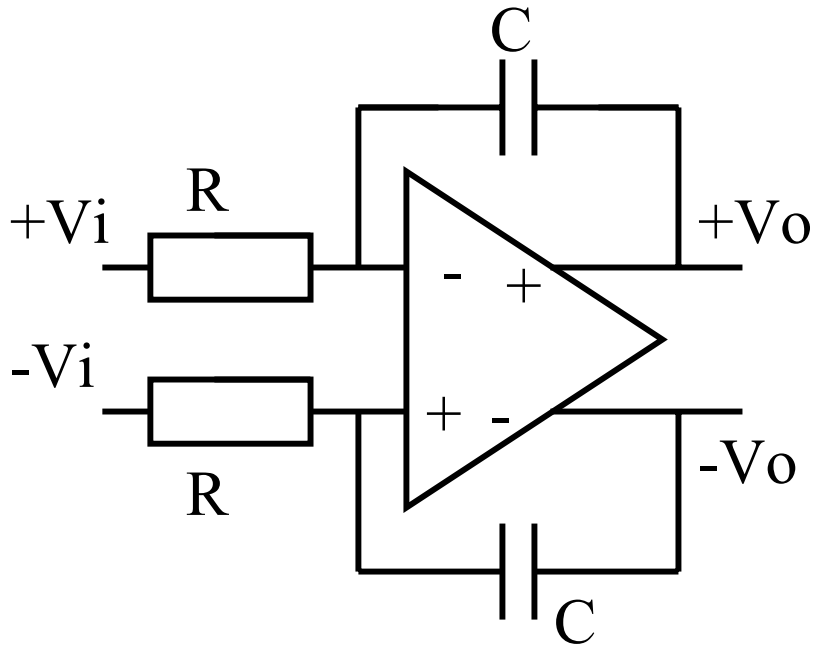
- Fully differential adder



$$V_o = -\frac{\beta_1(V_{c1} - V_T)}{\beta_2(V_{c2} - V_T)}(V_{i1} + V_{i2})$$

Basic Active RC Circuits

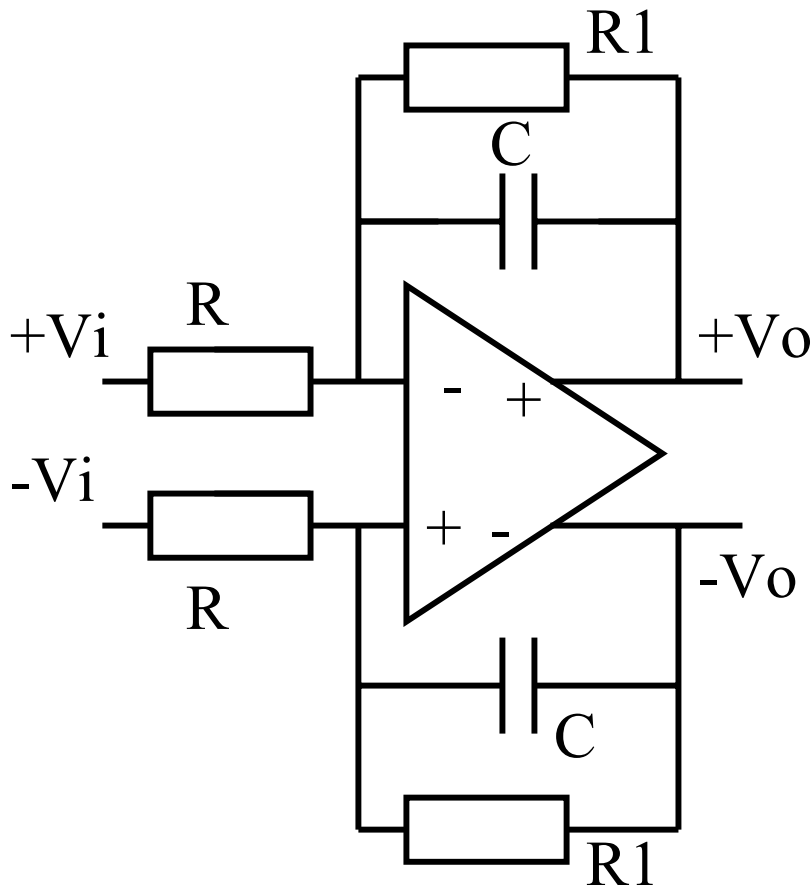
- Fully differential integrator



$$\frac{V_o}{V_i}(s) = -\frac{1}{RCs}$$

Basic Active RC Circuits

- Fully differential lossy integrator



$$\frac{V_o}{V_i}(s) = -\frac{1}{RCs + \frac{R}{R_1}}$$

